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Docket No.: 12412/1

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**APPLICANTS** 

Akio SATOU et al.

SERIAL NO.

(Natl. Phase of PCT/JP01/06131)

**FILED** 

29 March 2002

FOR

METHOD OF LASER BEAM MACHINING

**GROUP ART UNIT:** 

**EXAMINER** 

ASSISTANT COMMISSIONER FOR PATENTS Washington, D.C. 20231

#### PRELIMINARY AMENDMENT

SIR:

Prior to examination of the above-identified application, please enter the following amendments.

## In the Specification:

Page 7, line 10: Change "DISCLOSURE" to --SUMMARY--.

Page 10, line 1: Change "BEST MODE FOR CARRYING OUT THE INVENTION" to

-- DETAILED DESCRIPTION --.

### In the Claims:

Please amend the claims as follows:

1. (Amended) A method of laser beam machining, [characterized in that]



wherein a plurality of laser diode arrays are disposed in such a manner as to allow radiation of laser beams in a direction of a width of a part to be processed, and

[that] wherein each of the laser diode arrays is controlled in accordance with the direction of the width of the part to be processed so as to shape laser beams and irradiate the part to be processed with the laser beams.

2. (Amended) The method of laser beam machining according to claim 1, [characterized in that]

wherein each of the laser diode arrays is controlled and laser beams are shaped such that distribution of energy is changed in accordance with a width position of the part to be processed.

3. (Amended) The method of laser beam machining according to claim 2, [characterized in that]

wherein the distribution of energy is changed by controlling each of the laser diode arrays and shaping the laser beams such that laser beams with which the part to be processed is irradiated in its widthwise marginal portions exhibit a higher intensity than laser beams with which the part to be processed is irradiated in its widthwise central portion.

4. (Amended) The method of laser beam machining according to [any one of claims 1 to 3, characterized in that]